

REV.	MODIFICATION	DATE	DRAW
XA	INITIAL RELEASE	2021.02.03	Michael
XB	MODIF SPEC.	2021.06.18	Michael

HALOGEN FREE LEAD FREE

- NOTES
- MATERIAL:
 - HOUSING: THERMOPLASTIC UL94V-0
 - CONTACT: HIGH-PERFORMANCE COPPER ALLOY
 - LATCH: STAINLESS STEEL
 - PEG: STAINLESS STEEL
 - FINISH:
 - CONTACT: GOLD PLATING ON CONTACT AREA (SEE NOTE 4)
 - 1u"~3u" GOLD PLATING ON SOLDER AREA
 - NICKEL UNDER PLATING OVER ALL (SEE TABLE 1)
 - PEG: 50u"~150u" MATTE TIN PLATING OVER ALL
 - 50u"~150u" NICKEL UNDER PLATING OVER ALL
 - MSL LEVEL: MSL (MOISTURE SENSITIVITY LEVEL)=1
 - PART NO.: D5ARX-262XX-XX52
 - Ni PLATING SPEC SEE TABLE 1
 - CONTACT AREA PLATING SPEC
 - 01:GOLD 1u"Min.
 - 03:GOLD 3u"Min.
 - 05:GOLD 5u"Min.
 - 10:GOLD 10u"Min.
 - 15:GOLD 15u"Min.
 - 20:GOLD 20u"Min.
 - 30:GOLD 30u"Min.
 - PACKING: P-TAPE REEL
 - HOUSING COLOR: 1-BLACK 2-NATURAL

TABLE 1

N	A	0(NUMBER ZERO)	X
WITH "@LTK"	WITHOUT "@LTK"	WITH "@LTK"	TRADEMARK
90u"~150u"	50u"~150u"	50u"~150u"	CONTACT NICKEL FINISH
.X±0.35	.X*± 2'	.XX±0.25	.XXX±
			.XX*±

DIMENSION IN mm [Inch]	TOLERANCE UNLESS OTHERWISE SPECIFIED	PROD. SPEC. SP-D5XXXL1	PKG. SPEC. PK-D5XXX-XXX	APR. Kevin 2021.06.18	CHK. Andy 2021.06.18	DRA. Michael 2021.06.18

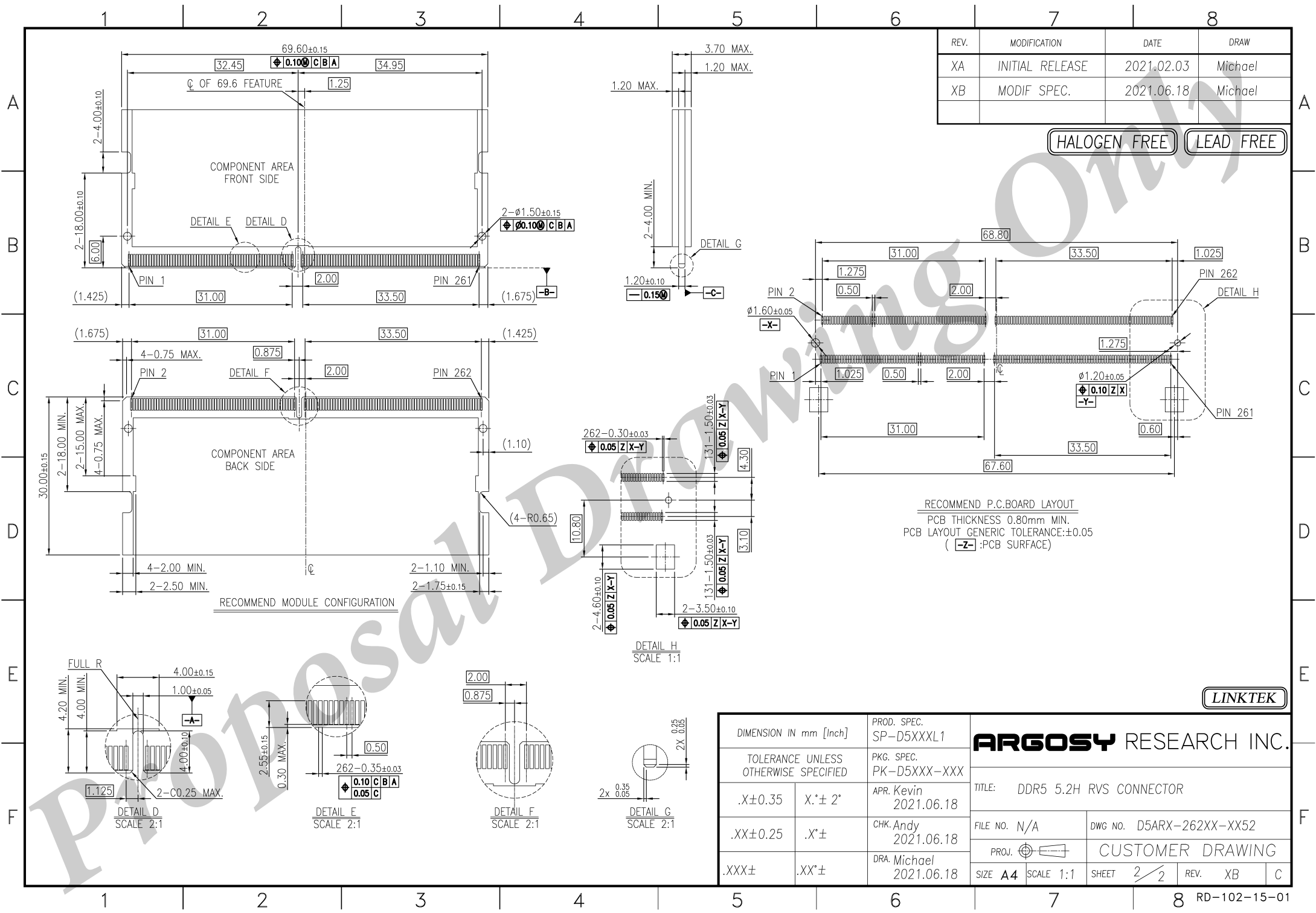
ARGOSY RESEARCH INC.

TITLE: DDR5 5.2H RVS CONNECTOR

FILE NO. N/A DWG NO. D5ARX-262XX-XX52

PROJ. CUSTOMER DRAWING

SIZE A4 SCALE 1:1 SHEET 1/2 REV. XB C



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RECOMMEND P.C.BOARD LAYOUT
 PCB THICKNESS 0.80mm MIN.
 PCB LAYOUT GENERIC TOLERANCE:±0.05
 (-Z- :PCB SURFACE)

LINKTEK

DIMENSION IN mm [Inch]		PROD. SPEC. SP-D5XXL1	ARGOSY RESEARCH INC.		
TOLERANCE UNLESS OTHERWISE SPECIFIED		PKG. SPEC. PK-D5XXX-XXX	TITLE: DDR5 5.2H RVS CONNECTOR		
.X±0.35	X.*± 2°	APR. Kevin 2021.06.18	FILE NO. N/A	DWG NO. D5ARX-262XX-XX52	
.XX±0.25	.X*±	CHK. Andy 2021.06.18	PROJ.	CUSTOMER DRAWING	
.XXX±	.XX*±	DRA. Michael 2021.06.18	SIZE A4	SCALE 1:1	SHEET 2/2 REV. XB C

A
B
C
D
E
F

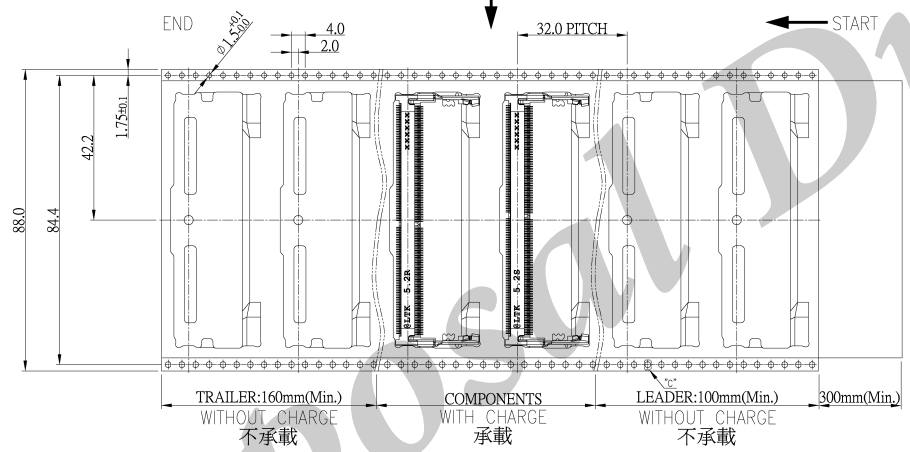
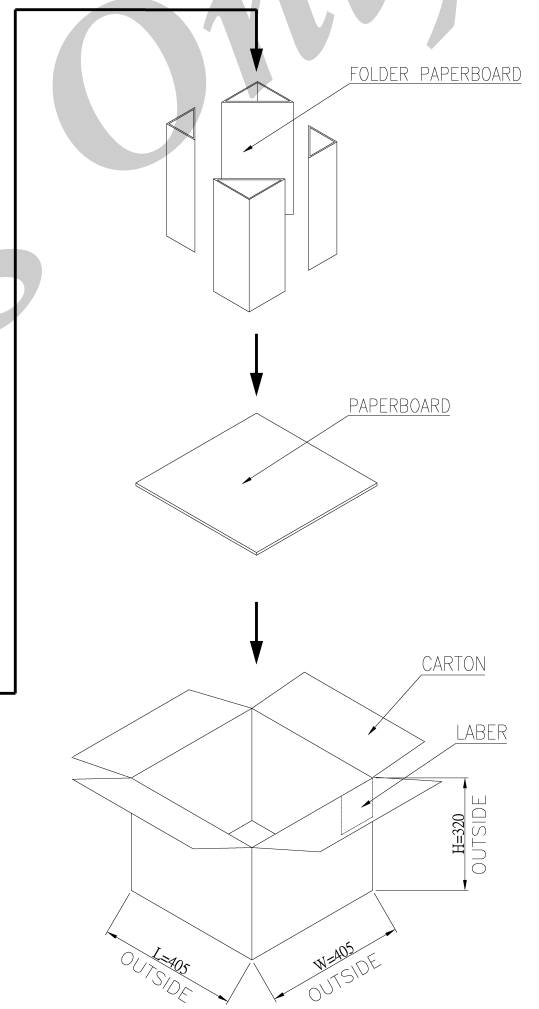
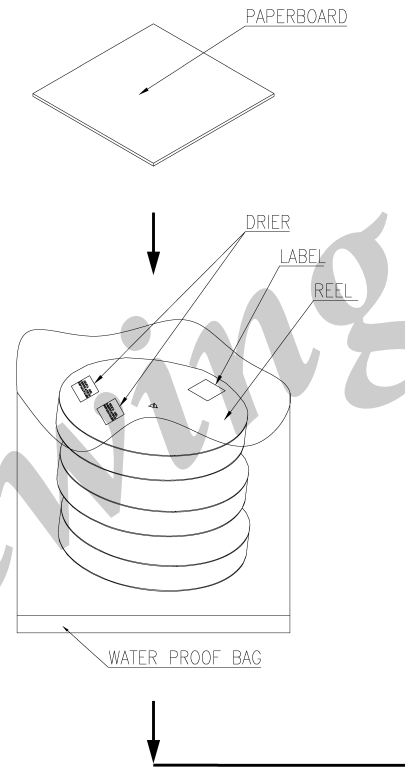
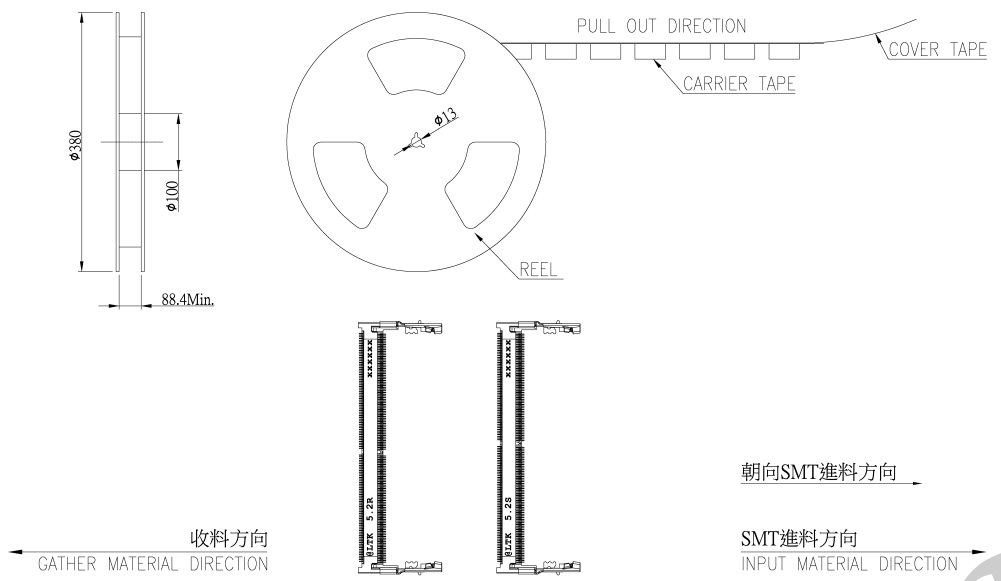
A
B
C
D
E
F

1 2 3 4 5 6 7 8

1 2 3 4 5 6 7 8 RD-102-15-01

HALOGEN FREE LEAD FREE

F
E
D
C
B
A



PART NO.	PCS/REEL	REEL/CARTON	PCS/CARTON
D5XR-262XX-XP52X	450	3	1.35K
D5XS-262XX-XP52X	450	3	1.35K

ARGOSY RESEARCH INC.	產品名稱 TITLE	PACKING FOR T/P DDR5 SO.DIMM CONNECTOR 5.2H REEL: 88.0 mm		案號 FILE NO.	N/A	更改 REV	XA	張數 SHEET	1 / 1	SIZE				
	包裝規範(PACKING LIST)	圖號 DWG. NO.	PK-D5XXX-003	審核 APPROVE	Kevin 2021.02.03	核對 CHECK	Andy 2021.02.03	製圖 DRAW	Michael 2021.02.03	A4	XA 更改 REV	INITIAL RELEASE 設變內容 MODIFICATION	2021.02.03 日期 DATE	Michael 修改 DRAW